03-29-2000



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B/O FORM	PTO 1595 (1/31/92)	U.S. Department of Commerce Patent and Trademark Office
	RECORDATION FO	rm Cover Sheet
	PATENT	
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To the Hono	orable Commissioner of Patents and Trademarks. Please reco	
	ame of Conveying Party(ies): ) Tomoharu KAJIYAMA	2. Name and Address of Receiving Party(ies):
(3	) Yuji MIYAHARA ) Katsuji MURAKAWA	Name: HITACHI, LTD.
	☐ Additional names of conveying parties attached	Internal Address:
3. N ⊠	ature of Conveyance:  Assignment   Merger	Street Address: 6, Kanda Surugadai 4-chome
	Security Agreement	City, State, Zip: Chiyoda-ku, Tokyo, Japan
(1) F	eution Date: ebruary 24, 2000 nd (3) February 25, 2000	
4. (a)	Patent Application Number(s):	4. (b) Patent Numbers:
	ume and Address of Party to whom Correspondence	umbers Attached. 09/527233  6. Total Number of Applications and Patents Involved: 1
Name:	oncerning this Document Should be Mailed:  Stanley P. Fisher	7. Total Fee: \$40.00 (37 C.F.R. § 3.41)
Address:	Reed Smith Hazel Thomas LLP 3110 Fairview Park Dr. Suite 1400 Falls Church, Va. 22042	<ul><li>⊠ Enclosed.</li><li>□ Authorized to be charged to deposit account.</li></ul>
		8. Deposit Account Number:
		ATTACH DUPLICATE COPY OF THIS PAGE IF PAYING BY DEPOSIT ACCOUNT
9. St	atement and Signature:	THIS SPACE
	the best of my knowledge and belief, the foregoing is true of coniginal document.	
_//	Wyn	March 16, 2000
Senlay Rol	jing reRostieration No. 24,344	(1)
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	1 1	Total number of pages comprising cover sheet: 4

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03/24/2000

PATENT REEL: 010635 FRAME: 0200

## ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## ADVANCED THERMAL GRADIENT DNA CHIP (ATGC), THE SUBSTRATE FOR ATGC, METHOD FOR MANUFACTURING FOR ATGC, METHOD AND APPARATUS FOR BIXOLEMICAL REACTION, AND STORAGE MEDIUM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside our signatures:

**RECORDED: 03/16/2000** 

	INVENTOR(S)	Date Signed
	(発明者フルネームサイン)	(署名日)
1) _	Tomoharu Kajiyama  Tomoharu Kajiyama  Jiyi Miyahara  Tomoharu Kajiyama  Yuji Miyahara	2/24/2000
	Tomoharu Kajiyama	•
2) _	Miyi Myalana	2/25/2000
	/ / Yuji Miyanara	, ,
3) _	Katsuji Murakawa	2/25/2000
	Katsuji Murakawa	
4) _		
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